

Product Change Notification

CHIP DIODES

Bourns Manufacturers Representatives Corporate Distributor Product Managers Americas Sales Team Asia Sales Team Europe Sales Team

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Bourns® Diode Products Addition of Second Wafer Fabrication Location and Support of "Green" Products

Bourns is adding a second wafer fabrication location, in the UK, for the diode part numbers below for continued secure supply chain management and delivery support to our customers.

Bourns P/N	Bourns P/N	Bourns P/N
CDS0D323-T03S	CDS0D323-T15S	CDNBS08-SRDA3.3-4
CDSOD323-T03SC	CDSOD323-T15SC	CDNBS08-SRDA05-4
CDS0D323-T05S	CDSOD323-T18S	CDNBS08-SRDA12-4
CDSOD323-T05SC	CDSOD323-T18SC	CDNBS08-SRDA15-4
CDS0D323-T08S	CDS0D323-T24S	CDNBS08-SRDA3.3-6
CDSOD323-T08SC	CDS0D323-T24S	CDNBS08-SRDA05-6
CDS0D323-T12S		CDS0T23-SR208
CDSOD323-T12SC		CDS0T236-T12LC

Bourns will implement a change to the Green Sumitomo G600 mold compound in the above packages as part of our plan to offer "Green" products to our customers in 2010.

Some products will be available in the new "Green" mold compound immediately if requested by customers.

Reliability data, SGS and MDS reports on the units' package assembly incorporating the above changes will be available on or before March 31, 2010.

Bourns is issuing 90 days notice that mass production using the above changes will begin May 1, 2010.